EXPO COMM WIRELESS JAPAN 2013

Date: May 29 - 31, 2013

Venue: Tokyo big sight, Tokyo, Japan

The largest and the only specialized exhibition in Wireless technologies, solutions and services in Japan

EXPO COMM WIRELESS JAPAN exhibition and conference, the leading wireless event in Japan, brought together the most prominent industry decision makers specializing in wireless mobile technologies and services. The three day B2B event was the 18th annual presentation demonstrating wireless technology, embedded technology and 4G/LTE Infrastructure and services. The exhibition covers applications and business solutions by smart phone for enterprise user as well. **Especially "Smart Phone" "Tablet device" and "Mobile cloud" will be the key**

device" and "Mobile cloud" will be the topics in 2013.

Furthermore EXPO COMM WIRELESS JAPAN also continue to feature short range wireless technologies such as

Wireless LAN, ZigBee, Bluetooth, and other short range wireless communication.

Participate in Japan's leading wireless B2B event!

As a specialized exhibition in which mobile and wireless industry professionals participate, EXPO COMM WIRLESS JAPAN brings carriers, manufacturers, technology users and enterprise users together to connect on several levels involving wireless / Mobile technologies and services.

If you are seeking to:

- -Discover new business opportunity
- -Increase your sales though meetings with customers
- -Expand your partner and distributor base
- -Emphasize your brand positioning

EXPO COMM WIRELESS JAPAN acts as a meeting place for wireless industry professionals. The exhibition showcased 180 companies and drew a record breaking attendance of over 55,000 visitors in 2012. The event connected mobile and wireless communication professionals, technology providers, manufacturers, as well as enterprise users.

Exhibit category

- -Mobile terminal: Smart phone, Tablet device, Mobile phone, Handy terminal, data card, etc.
- -WIRELESS WAN SYSTEM: LTE, LTE-Advanced, WiMAX, MVNO, basement technology, etc.
- -WIRELESS LAN /PAN SYSTEM: wireless LAN, ZigBee, Bluetooth, ANT, Z-wave, sensor, etc.
- **-DEVICE / SOFTWARE:** Application processor, Battery, OS/Middleware, Module, testing equipment, etc.
- -Content, Application: Navigation, Map, GIS, GPS, Game, Marketing solution, etc.
- **-SOLUTION for enterprise use:** Mobile system integration service, Module, Handy terminal, IC tag, network security, sensing equipment etc.

Features in 2013

Smart Device plus

Smart phone, Tablet device, Mobile phone, Handy terminal, data card, Solution for enterprise use, MDM, BYOD, Security, etc.

LTE-Advanced EXPO

Wireless broadband system, Wireless WAN, MAN technologies, Base station technologies, MIMO, testing tools, VoLTE, Traffic off-load, etc.

Short Range Wireless EXPO

Wireless LAN, NFC, Bluetooth, ZigBee, TransferJet, Z-wave, DECF, WiGig, etc. GIS, Wireless LAN / PAN, etc.

SAMRT M2M EXPO

M2M, Wireless sensor, low power consumption technologies, Wireless power transmission, Energy Harvesting, etc.

Smartphone & Mobile phone Dealers EXPO

Retail management software, shop design simulation soft, mobile phone accessary, etc.

Targeted visitor

- -Enterprise: Division of management, marketing, product planning, information.
- -ICT related industry: Division of management, product planning, Engineering, R&D, technical

Outline

Date: May 29-31, 2013

Venue: Tokyo Big Sight, Tokyo, Japan

Japan's leading wireless B2B

Participate in

event!

Organized by EJK Japan., Ltd / RIC Telecom Co., ltd

Endorsed by Ministry of Internal Affairs and Communications / The ITU Association of Japan Inc. / Association of Radio Industries & Business / Telecommunications Carriers Association/ Internet Association Japan / YRP R&D Promotion Committee / ASP•SaaS Industry Consortium/ The Association for Promotion of Digital Broadcasting / Communications and Information Network Association of Japan (CIAJ) / Digital Content Association of Japan / Support Center for Advanced Telecommunications Technology Research, Foundation (SCAT) / Telecom Services Association / Japan IC Card System Application Council / Japan Internet Providers Association/ Japan Automatic Identification Systems Association / NPO Japan Network Security Association/ Japan Cable and Telecommunications Association / Telecom Engineering Center (TELEC)/ Association of Media in Digital / Shop System Study Society / Japan Chain Stores Association / Japan Department Stores Association / Japan Council of Shopping Centers

Supported by Mobile Computing Promotion Consortium (MCPC) / Mobile Content Forum (MCF) / Mobile Marketing Solution Association (MMSA) / Japan Marketing Association (JMA) / ZigBee Alliance / ZigBee SIG-J

Co-held exhibitions

LTE-Advanced EXPO

Outline

Use of smartphones and tablet devices increase data traffic volume. They have a big impact on capacity of wireless communication network. As mobile cloud service expands, it causes obviously big data traffic to the wireless network and the network is going to become tight.

Since wireless network has become an important social infrastructure, reliability of wireless network has been crucial. LTE-Advanced EXPO will focuses on wireless telecommunication infrastructure to provide high service quality. The EXPO showcase equipment, system of the wireless telecom infrastructure for developing services.

Exhibit product category

LTE-Advanced, WiMAX, HSPA, MIMO, next generation wireless LAN, Radio on fiber, satellite communication, security, authentication, power supply and battery, Telecom platform as a Service, Infrastructure as a Service, data Traffic off-load, etc.

Short Range Wireless EXPO

Outline

The EXPO features technologies, services and solutions of short range wireless communication. The EXPO will further enhance expanding products in the short range wireless industry. It is a place where exhibitors and visitors can exchange information about cutting edge products and manufacturing solutions, driving an increase in the number of buyers.

Exhibit product Category Exhibit category

Next Generation Wireless LAN, Wi-Fi, Bluetooth, ZigBee, Z-wave, DECT, ANT, NFC, Security,

IMES(indoor messaging system), wearable computing, etc.

Smart M2M EXPO

Outline

After wireless broadband and cloud computing become popular, M2M, machine to machine, which connect objects by wireless / sensor network, has capability to access to cloud computing network. This network model can be used for helping analysis of big data and its market is expanding.

M 2 M cloud is getting attention as new ICT infrastructure in the advanced information society.

"Mobile power expo" was first organized in 2010 as a co-held show with EXPO COMM WIRELESS JAPAN2010. The Mobile power expo focused attention on mobile/wireless technology that penetrated in several industries, and launched new service and new business.

While M2M was expanding its market in near past, we develop "Mobile power expo" to "M2M cloud EXPO" in 2012, considering the new development phase of M2M.

In 2013, The M2M cloud EXPO will focus on M2M platform and related technologies such as wireless / sensor network, cloud computing, energy harvesting, etc.

Exhibit product Category

System solution · · · · business system, cloud solution

Telecommunication · wireless LAN / PAN, NFC, sensor network

M2M device ·····module, sensor, Wi-Fi direct

Testing tool·····analysing tool, monitoring tool, simulator Others wireless power transmission,

Energy harvesting technology

Co-held exhibitions

Smartphone & Mobile phone Dealers EXPO

Outline

A lot of Mobile phone shop visit EXPO COMM WIRELESS JAPAN to study the latest smart phone and applications. In 2012, we plan to take this product category out of EC Wireless Japan to make more efficient business communication between targeted exhibitor and visitor.

Exhibit product Category Retail management software, shop design simulation soft, mobile phone accessary, etc.

Exhibit survey: How many business card did you get and gain good business prospective in future?

Gained business cards

#1:2000 cards #2:1300 cards #3: 700 cards



Business prospective in future

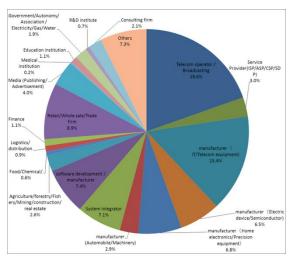
#1:100 #2: 50 #3: 40

Attendee profile in 2012

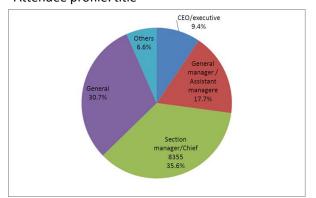
■visitor number in 2012

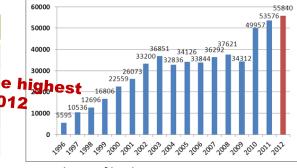
| date | Number | (numbe | r in 2011) |
|----------------------|--------|----------|---------------------------|
| May 30 th | 16,437 | (16,896) | _ |
| May 31 st | 17,959 | (17,434) | Recorded the number in 20 |
| June 1 st | 21,444 | (19,246) | moer in 20 |
| Total | 55,840 | (53,576) | |

Attendee profile: industry

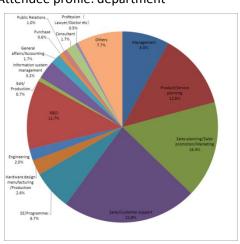


Attendee profile: title

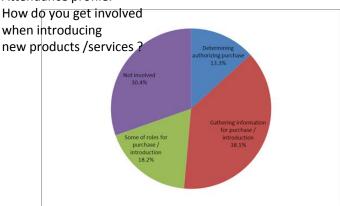




Attendee profile: department

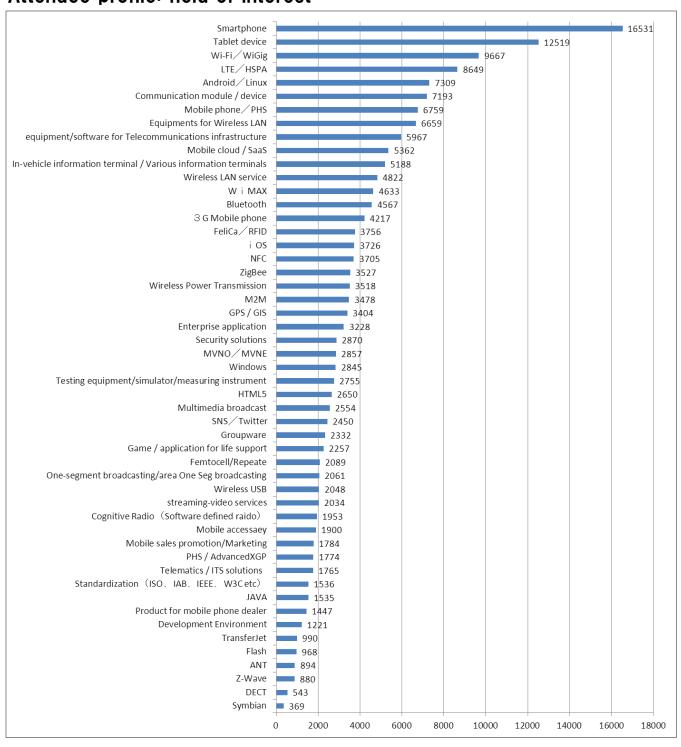


Attendance profile:



Attendee profile in 2012

Attendee profile: field of interest



Exhibitor list in 2012

Exhibitor list Exhibitor number: 180 companies

ADC Technology inc. / Altima Corp. / Amimon Japan / Aplix Corporation / Appli-Smart Co., Ltd. / ARTO Co., Ltd. / BCN Inc. / Be-CUBE / Broadleaf Co., Ltd. / Brother Sales, Ltd. / BSC, Ltd. / BASOCOM Technologies, Inc. / Case-Mate / CASIO COMPUTER CO., LTD. / CETECOM JAPAN K.K. / Changzhou Wujin Fengshi Communication Equipment Co., Ltd / Collaborative R&D Project of Kyoto Univ., The Univ. of Electro-Communications, and Kobe Digital Labo Inc. / Commscope(Andrew Japan) / ComWorth Co., Ltd / CORE CORPORATION / COSMO Sound inc. / CQ Publishing Co., Ltd. / CyberWing Corporation / DBG HOLDINGS LIMITED / DECT Forum Japan Working Group(SAGEMCOM, Dialog Semiconductor, DSP Group, NEC, Panasonic System Networks Co., Ltd., Uniden Corporation, Lantiq) / Dempa Times Co., Ltd. / Denki Kogyo Company, Ltd / DENSO Corporation / / Digi International K.K. / / EJK Japan, Ltd / Energy Harvesting Consortium / E-net Corporation / Ericsson Japan K.K / ESUKEI CO.,LTD. / FOX.INC. / Futaba Corporation / GainSpan Corporation(Altima Corp., Ryoyo Electro Corporation, Hakuto Co.,Ltd., SATORI ELECTRIC CO.,LTD.) / HAKUBA PHOTO INDUSTRY CO., LTD. / HUAWEI TECHNOLOGIES JAPAN K.K. / i.Tech Dynamic Global Distribution Limited / i-BROADCAST INC. / Impress R&D / INCOM Co., Ltd. / Industrial Forum for Mobile Socialize Systems / Infinitegra, Inc. / INSIGHT SIP SAS / InternetITS Consortium / INTERNIX Inc. / Internrt Initiative Japan Inc. / IPNetfusion K.K. / Iscas, inc. / ISUZU MOTORS LIMITED / Japan Android Group / Japan System Project Co., Ltd. / J-Spin Inc. / Kanematsu Communications Limited / KDDI CORPORATION / KYOCERA CORPORATION / LIGHTSPEED INTERNATIONAL CO. / m&m Research Inc. / MCCI Corporation / MCPC Mobile M2M Working Group / Menix Co.,Ltd. / Mentum / MITSUMI ELECTRIC CO., LTD. / Mobile Computing Promotion Consortium / Mobile Content Forum / Mobile Iron Japan / MobileEco CO., Ltd / MTI.Ltd. / NAVITIME JAPAN Co., Ltd. / NEC Corporation / NEC Engineering, Ltd. / Network Value Components, Ltd. / New Generation M2M Consortium / NEXCOM JAPAN Co. Ltd / Nihon Dengyo Kosaku Co., Ltd. / Nikkei Business Publications, Inc. / NIPPON TELEGRAPH AND TELEPHONE EAST CORPORATION / NISHIKEN CO., LTD / Nokia Siemens Networks Japan Corp./ Nordic Semiconductor ASA / NP System Development Co., Ltd. / NTT Communications Corporation / NTT DATA CORPORATION / NTT DATA MSE CORPORATION / NTT DOCOMO, Inc. / OKAMOTO ELECTRONICS CORPORATION / OSAKA GAS CO.,LTD. / OSMA LIMITED / OTSL Inc. / Panasonic System Networks Co., Ltd. / PicoCELA Inc. / Pioneer Sales & Marketing Corporation. / RAILWAY INFORMATION SYSTEMS CO., LTD. / RASTABANANA Co., Ltd. / RIC Telecom Corpration / Rikei Corp. / / SAGEMCOM / SATORI ELECTRIC Co., Ltd. / SATORI ELECTRIC CO., LTD. / SDV CARSOLUTIONS CO., Ltd. / Sigma Designs Japan, KK / Silent Street Music Performance / SIMCom Wireless Solutions / SMILEWORLD CO.,LTD. / Sonix Co.,Ltd. / Spinner Telecommunication Devices(Shanghai) Co.,Ltd. / STAR COMMUNICATIONS K.K. / SUNCREST Co.,Ltd. / SYSTEC CO.,LTD. / SYSTECH-ONE CO., LTD. / TEEMA pavilion(Taiwan Electrical and Electronic Manufacturers' Association, Rayco Electronics, Canmore Electronics Co., Ltd., LIGHTSPEED INTERNATIONAL CO., Lucent Trans Electronics Co., Ltd., Topcom Technology Co., Ltd., UniTraQ International Corporation) / TEPCO UQUEST,LTD. / Texas Instruments Japan / The Distribution Systems Research Institute / / TOKYO KEIKI INC. / TransferJet Consortium / UbiNavi Co., Ltd. / u-blox Japan KK / UD Trucks Corporation / UL Japan, Inc / WORKSTUDIO. Corp / YAGAMI INC. / YRP R&D Promotion Committee / YUASA Co., Ltd. / ZACTA Technology Corporation / Zeemote / Zigbee Alliance&SIG Japan pavilion(NEC Engineering, Ltd., Ad-Sol Nissin Corp., Oki Electric Industry Co., Ltd., Digi

Highlights of the show in 2012

International K.K., TÜV Rheinland Japan Ltd., Tokyo Cosmos Electric Co., Ltd.)

Increase of 4.2% in total attendance compared with the 2011.

Increase of 5% in total exhibitors.

Total attendance of the show is 55,840

Asia Wireless Summit was held. Major carriers from India, Vietnam, South Korea and Japan participate in morning sessions and global network solution companies to be speakers in afternoon sessions.

Attendance visited from 13 countries

320 press visited the show and reported throughout Japan.

Exhibited from 9 countries

EXHIBIT FEE

Raw Space:

Exhibit less than 18sqm: US\$676 per sqm
Exhibit more than 18sqm: US\$630 per sqm
*available from 9 sqm and above

All of fee are included in tax.



Package Booth:

Available in 9 sqm units: USD7,686 per unit

Package booth including; exhibit space, White wall, Carpet, Company Signboard, registration counter, chair(2), Fluorescent light, 800W ac adapter, trash box, booth cleaning during the exhibition period

Sponsorship Seminar: It is your presentation opportunity.

For exhibitor US\$ 7,000 / one slot

For un-exhibitor US\$ 14,000 / one slot

■Time: 50 minutes long ■Seat: 120 seated

- Registration: Audience will be required pre-registration through official web site.
- ■Audience personal data will be given to speaker after the exhibition.
- ■Presentation equipment are included in price.(PA and screen)
- Promoted in "Attendee flyer" "Official Web site" and "e-mail campaigns" e.g.
- ■Interpreter fee IS NOT INCLUDED.

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